

Applic. No. : 10/090,289

In the Claims:

Claim 1 (amended). An electronic component, comprising:

at least two wiring boards stacked on top of one another and substantially parallel to one another, and at least one of said at least two wiring boards having apertures formed therein;

at least two semiconductor chips each mounted on a respective wiring board of said at least two wiring boards and electrically connected to said respective wiring board; and solder connections mechanically and electrically interconnecting said at least two stacked wiring boards, said soldered connections extending through said apertures in at least one of said at least two stacked wiring boards and over one or more levels of said at least two stacked wiring boards.

Claim 15 (amended). A method for producing an electronic component, which comprises the steps of:

providing at least two wiring boards having electrical contacts disposed thereon and at least two semiconductor chips each mounted on and electrically connected to a respective wiring board of the at least two wiring boards, and at least one of the wiring boards having apertures formed therein; depositing solder in the apertures of the wiring boards;

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stacking the wiring boards substantially parallel; and
melting the solder resulting in solder connections
mechanically and electrically interconnecting the at least two
stacked wiring boards, the solder connections extending
through the apertures in at least one of the at least two
wiring boards and over one or more levels of the at least two
stacked wiring boards.

Claim 16 (amended). The method according to claim 15, which
comprises providing the solder in the apertures in a form of
solder balls having a smaller diameter than the apertures.

Claim 17 (amended). The method according to claim 15, which
comprises providing the solder in the apertures in a form of
solder paste.

Enter the Following New Claims:

-- 21. The method according to claim 15, wherein the
apertures are provided near an edge of the at least two wiring
boards.

21. The method according to claim 15, further comprising
applying supporting points to rear sides of the at least two
wiring boards facing away from the semiconductor chips. --